

AMENDMENT TO THE CLAIMS

1-12. (Canceled)

13. (Currently amended) A circuit board manufacturing method comprising the steps of:

forming a through hole on an insulator layer and then filling said through hole with a conductive paste;

dispersing and forming a protective agent [[in mottle-like]] on an adhesion surface of a conductor foil ~~which provides a wiring layer, and dispersing and forming each dimension of so as to include~~ adhesion surface regions where said protective agent does not exist ~~in a state that the plurality of said conductive powder constituting said conductive paste is set to be capable of abutting on the said wiring layer;~~

sticking said conductor foil to said insulator layer; and

~~electrically and physically joining said conductor foil and said conductive paste by abutting [[the]] a plurality of [[said]] conductive powders constituting the conductive paste and said conductor foil to each other through the adhesion surface regions by means of heating and pressurizing [[for]] said insulator layer and conductor foil.~~

14. (Currently amended) The circuit board manufacturing method according to claim 13, wherein said protective agent is stored and placed into a minute recess in said adhesion surface by abutting [[a adhesive]] said adhesion surface of said conductor foil on a protective agent containing liquid, while a storage amount of said protective agent for said minute recess is controlled by adjusting an abutting time of said protective agent containing liquid, thereby

setting [[each]] a dimension of the adhesion surface regions where said protective agent does not exist.

15. (Currently amended) The circuit board manufacturing method according to claim 13, wherein said protective agent is stored and placed into [[the]] a minute recess in the adhesion surface by abutting the adhesion surface of said conductor foil on the protective agent containing liquid, while [[the]] a storage amount of said protective agent for said minute recess is adjusted by adjusting a protective agent containing amount of said protective agent containing liquid, thereby setting [[each]] a dimension of the adhesion surface regions where said protective agent does not exist.

16. (Currently amended) The circuit board manufacturing method according to claim 13, wherein a layer containing said protective agent is formed on the adhesion surface of said conductor foil, and then the protective agent layer is polished to such an extent that a top portion of a minute protrusion on said adhesion surface [[may be]] is exposed, while [[a]] an exposed amount of said top portion is adjusted at a time of polishing, thereby setting [[each]] a dimension of the adhesion surface regions where said protective agent does not exist.